



MJ N-Channel Enhancement Mode Power MOSFET

Description

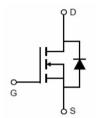
The MJ30H11BG uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

General Features

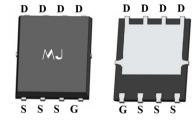
- ♦ Vps=30V.lp=110A $R_{DS(ON)}$ <2.3m Ω (typical) @ V_{GS}=10V $R_{DS(ON)}$ <3.3m Ω (typical) @ V_{GS}=4.5V
- Excellent gate charge x RDS(on) product(FOM)
- ◆ Very low on-resistance R_{DS(on)}
 ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ♦ 100% UIS tested

Application

- ♦ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification







Top View

Bottom View

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30H11BG	MJ30H11BG	DFN 5X6 -8L	-	-	-

Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	110	А
Drain Current-Continuous(Tc =100℃)	ID(100°C)	77.8	А
Pulsed Drain Current	IDM	440	А
Maximum Power Dissipation	Po	68	W
Single pulse avalanche energy (Note 5)	Eas	350	mJ
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	1.83	°C/W	
---	------	------	------	--





Electrical Characteristics (T_A =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	loss	Vps=30V,Vgs=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	_	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	1	1.6	2.5	V
		V _{GS} =10V, I _D =20A	-	2.3	3.0	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =4.5V, I _D =20A	-	3.3	4.1	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	50	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	Clss		-	3009	-	PF
Output Capacitance	Coss	F=1.0MHz	-	451	-	PF
Reverse Transfer Capacitance	Crss		-	403	-	PF
Switching Characteristics (Note 4)			ı			
Turn-on Delay Time	t _{d(on)}		-	20	-	nS
Turn-on Rise Time	tr	V _{DD} =15V,I _D =20A V _{GS} =4.5V,R _{GEN} =1.8Ω	-	15	-	nS
Turn-Off Delay Time	t _{d(off)}		-	60	-	nS
Turn-Off Fall Time	tr		-	10	-	nS
Total Gate Charge	Qg		_	66.3	-	nC
Gate-Source Charge	Qgs	V _{DS} =15V,I _D =20A, V _{GS} =10V	_	7	_	nC
Gate-Drain Charge	Qgd	-	-	17.2	_	nC
Drain-Source Diode Characteristics						<u> </u>
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =20A	_	_	1.2	V
Diode Forward Current (Note 2)	Is		-	-	110	А
Reverse Recovery Time	trr		_	56	_	nS
Reverse Recovery Charge	Qrr	TJ=25°C, IF=20A di/dt=100A/µs ^(Note 3)	_	110		nC
	Scii			'''		'10

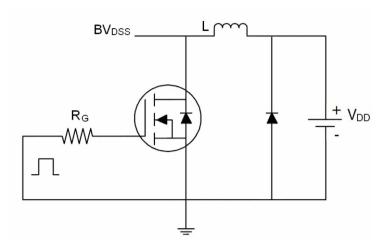
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t≤10sec.
- 3 Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%.
- 4 Guaranteed by design, not subject to production
- \bigcirc EAS condition: Tj=25°C,VDD=15V,VG=10V,L=0.5mH,Rg=25 Ω

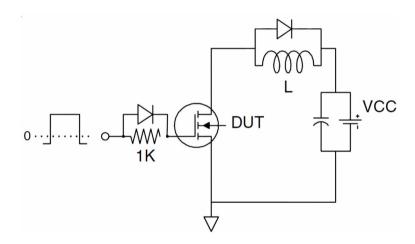




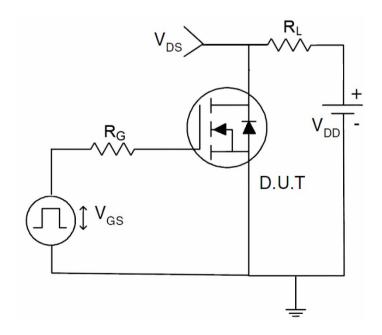
Test circuit



Eas test Circuit



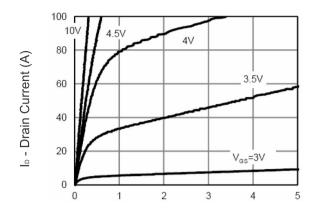
Gate charge test Circuit



Switch Time Test Circuit

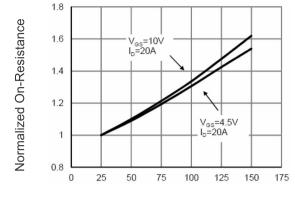


Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



 T_J -Junction Temperature(${}^{\circ}C$)

Figure 4 Rdson-JunctionTemperature

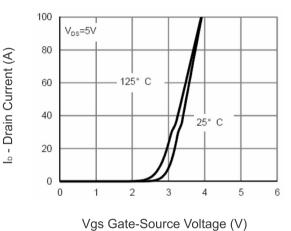
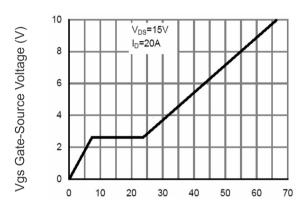


Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

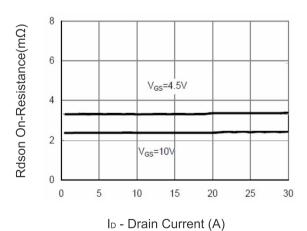
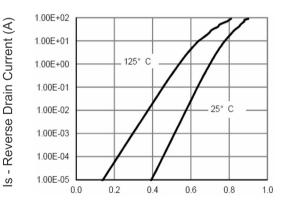


Figure 3 Rdson- Drain Current



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



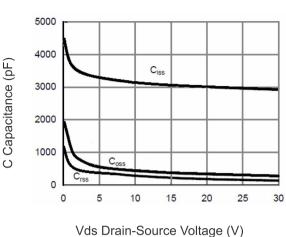


Figure 7 Capacitance vs Vds

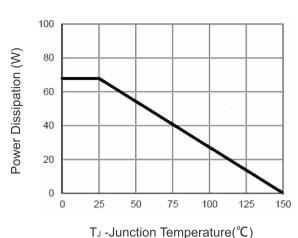
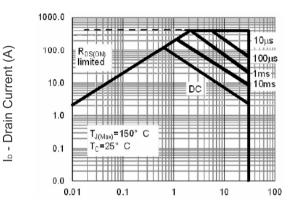
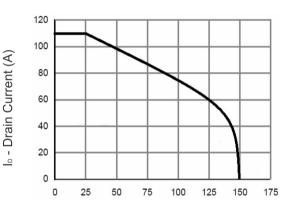


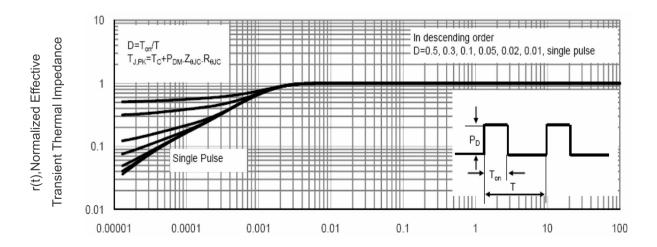
Figure 9 Power De-rating



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 Current De-rating



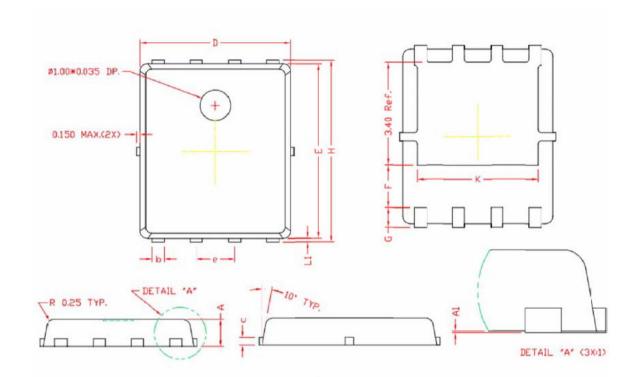
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





DFN5X6-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

CUMBOL	MIN	NOW	MAY	
SYMBOL	MIN	NOM	MAX	
A.	0.80	0.90	1.00	
A1	0.00	0.03	0.05	
b	0.35	0.42	0.49	
С	0. 254 REF.			
D	4.90	5.00	5. 10	
F	1. 40 REF.			
E	5. 70	5. 80	5. 90	
е	1. 27 BSC.			
Н	5. 95	6.08	6. 20	
L1	0.10	0.14	0. 18	
G	0.60 REF.			
K	4. 00 REF.			





Attention:

Any and all MJ power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MJ power representative nearest you before using any MJ power products described or contained herein in such applications.

MJ power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MJ power products described or contained herein.

Specifications of any and all MJ power products described or contained herein stipulate the erformance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MJ power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all MJ power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or therwise, without the prior written permission of MJ power Semiconductor CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MJ power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MJ power product that you intend to use.

This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.